Material Declaration Report

Package Type:	BQSOP 80L
Pericom Package Code:	B80(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	324.000
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	2
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	12/2/2008

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
			Silica Fused	60676-86-0	90.800	221.7935
MOLD COMPOUND	244.266	OSE	Epoxy Resin 1	Proprietary	3.000	7.3280
			Phenolic Resin	Proprietary	3.000	7.3280
			Epoxy Resin 2	Proprietary	2.000	4.8853
			Aromatic Phosphate	Proprietary	1.000	2.4427
			Carbon Black	1333-86-4	0.200	0.4885
			Silica Fused	60676-86-0	88.000	214.9541
		SPEL	Epoxy Resin	Proprietary	5.000	12.2133
			Phenolic Resin	Proprietary	4.500	10.9920
			Epoxy, Cresol Novolac	29690-82-2	2.000	4.8853
			Carbon Black	1333-86-4	0.500	1.2213
			Copper	7440-50-8	97.021	64.3684
LEADFRAME	66.345		Iron	7439-89-6	2.350	1.5591
			Silver	7440-22-4	0.453	0.3007
			Zinc	7440-66-6	0.111	0.0735
			Phosphorus	7723-14-0	0.065	0.0431
SILICON DIE	5.083		Silicon (Si)	7440-21-3	99.192	5.0416
			Non-hazardous Metal	Proprietary	0.808	0.0411
			Silver	7440-22-4	76.000	0.4039
DIE ATTACH EPOXY	0.531	OSE	Acrylic Resin	Proprietary	8.000	0.0425
			Acrylate	Proprietary	5.500	0.0292
			Polybutadiene derivative	Proprietary	5.500	0.0292
			Epoxy resin	Proprietary	2.500	0.0133
			Additive	Proprietary	1.000	0.0053
			Butadiene copolymer	Proprietary	1.000	0.0053
			Peroxide	Proprietary	0.500	0.0027
			Silver	7440-22-4	80.000	0.4252
		SPEL	Epoxy Resin	9003-36-5	10.000	0.0532
			Diluent	26447-14-3	6.000	0.0319
			Hardener	620-92-8	3.500	0.0186
			Dicyandamide	461-58-5	0.500	0.0027
GOLD WIRE	1.027		Gold(Au)	7440-57-5	99.990	1.0264
			Impurities	-	0.010	0.0001
SOLDER PLATING	6.748		Tin (Sn)	7440-31-5	99.990	6.7474
			Impurity	-	0.010	0.0007

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
Device	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb <1000ppm	Hg <1000ppm	Cr+6 <1000ppm	Cd <100ppm	PBB <1000ppm	PBDE <1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.